

## P-Channel 40 V (D-S) MOSFET

PRODUCT SUMMARY	
V <sub>DS</sub> (V)	-40
R <sub>DS(on)</sub> (Ω) at V <sub>GS</sub> = -10 V	0.012
R <sub>DS(on)</sub> (Ω) at V <sub>GS</sub> = -4.5 V	0.015
I <sub>D</sub> (A)	-50
Configuration	Single

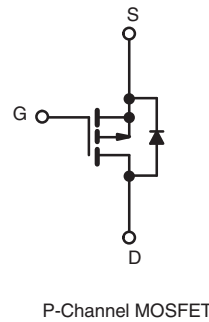
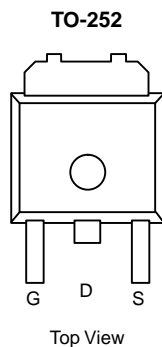
### FEATURES

- TrenchFET® power MOSFET
- Package with low thermal resistance
- 100 % R<sub>G</sub> and UIS tested

AUTOMOTIVE  
GRADE



RoHS  
COMPLIANT  
HALOGEN  
FREE



ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub> = 25 °C, unless otherwise noted)				
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-Source Voltage		V <sub>DS</sub>	-40	V
Gate-Source Voltage		V <sub>GS</sub>	± 20	
Continuous Drain Current	T <sub>C</sub> = 25 °C <sup>a</sup>	I <sub>D</sub>	-50	A
	T <sub>C</sub> = 125 °C		-39	
Continuous Source Current (Diode Conduction) <sup>a</sup>		I <sub>S</sub>	-50	
Pulsed Drain Current <sup>b</sup>		I <sub>DM</sub>	-200	
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	-40	
Single Pulse Avalanche Energy		E <sub>AS</sub>	80	
Maximum Power Dissipation <sup>b</sup>	T <sub>A</sub> = 25 °C	P <sub>D</sub>	3	W
	T <sub>C</sub> = 25 °C		136	
	T <sub>C</sub> = 125 °C		45	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-Ambient	PCB Mount <sup>c</sup>	R <sub>thJA</sub>	50	°C/W
Junction-to-Case (Drain)		R <sub>thJC</sub>	1.1	

### Notes

- Package limited.
- Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2 %.
- When mounted on 1" square PCB (FR4 material).
- Parametric verification ongoing.

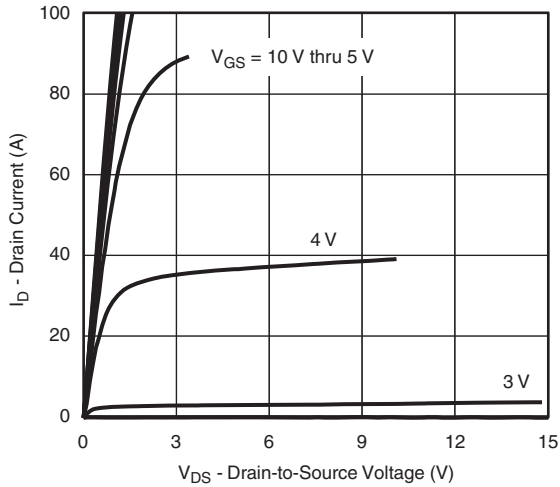
SPECIFICATIONS ( $T_C = 25\text{ }^\circ\text{C}$ , unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
<b>Static</b>							
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0\text{ V}, I_D = -250\text{ }\mu\text{A}$	-40	-	-	V	
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\text{ }\mu\text{A}$	-1.5	-	-2.5		
Gate-Source Leakage	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$	-	-	$\pm 100$	nA	
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{GS} = 0\text{ V}$	$V_{DS} = -40\text{ V}$	-	-	-1	$\mu\text{A}$
		$V_{GS} = 0\text{ V}$	$V_{DS} = -40\text{ V}, T_J = 125\text{ }^\circ\text{C}$	-	-	-50	
		$V_{GS} = 0\text{ V}$	$V_{DS} = -40\text{ V}, T_J = 175\text{ }^\circ\text{C}$	-	-	-150	
On-State Drain Current <sup>a</sup>	$I_{D(on)}$	$V_{GS} = -10\text{ V}$	$V_{DS} \leq -5\text{ V}$	-50	-	-	A
Drain-Source On-State Resistance <sup>a</sup>	$R_{DS(on)}$	$V_{GS} = -10\text{ V}$	$I_D = -17\text{ A}$	-	0.012	0.014	$\Omega$
		$V_{GS} = -10\text{ V}$	$I_D = -50\text{ A}, T_J = 125\text{ }^\circ\text{C}$	-	-	0.017	
		$V_{GS} = -10\text{ V}$	$I_D = -50\text{ A}, T_J = 175\text{ }^\circ\text{C}$	-	-	0.020	
		$V_{GS} = -4.5\text{ V}$	$I_D = -14\text{ A}$	-	0.015	0.018	
Forward Transconductance <sup>a</sup>	$g_{fs}$	$V_{DS} = -15\text{ V}, I_D = -17\text{ A}$	-	61	-	S	
<b>Dynamic <sup>b</sup></b>							
Input Capacitance	$C_{iss}$	$V_{GS} = 0\text{ V}$	$V_{DS} = -25\text{ V}, f = 1\text{ MHz}$	-	2872	3950	$\mu\text{F}$
Output Capacitance	$C_{oss}$			-	508	635	
Reverse Transfer Capacitance	$C_{rss}$			-	352	440	
Total Gate Charge <sup>c</sup>	$Q_g$	$V_{GS} = -10\text{ V}$	$V_{DS} = -30\text{ V}, I_D = -50\text{ A}$	-	60	80	nC
Gate-Source Charge <sup>c</sup>	$Q_{gs}$			-	5.7	8.6	
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$			-	14.7	22	
Gate Resistance	$R_g$	f = 1 MHz		1.5	3	4.5	$\Omega$
Turn-On Delay Time <sup>c</sup>	$t_{d(on)}$	$V_{DD} = -20\text{ V}, R_L = 0.4\text{ }\Omega$ $I_D = -50\text{ A}, V_{GEN} = -10\text{ V}, R_g = 1\text{ }\Omega$		-	10	15	ns
Rise Time <sup>c</sup>	$t_r$			-	12	18	
Turn-Off Delay Time <sup>c</sup>	$t_{d(off)}$			-	40	60	
Fall Time <sup>c</sup>	$t_f$			-	16	24	
<b>Source-Drain Diode Ratings and Characteristics <sup>b</sup></b>							
Pulsed Current <sup>a</sup>	$I_{SM}$			-	-	-200	A
Forward Voltage	$V_{SD}$	$I_F = -50\text{ A}, V_{GS} = 0\text{ V}$		-	-1	-1.5	V

**Notes**

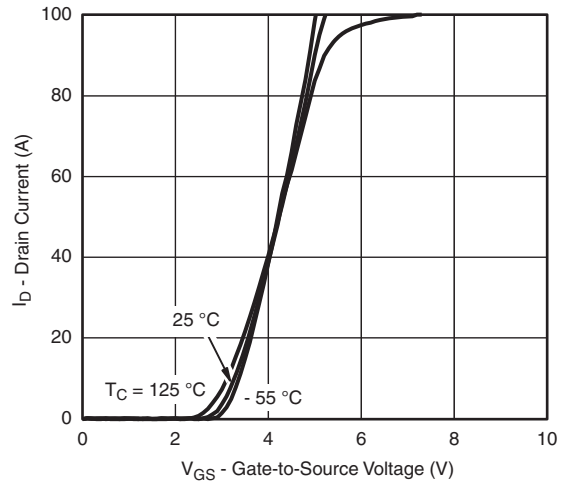
- a. Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ .
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

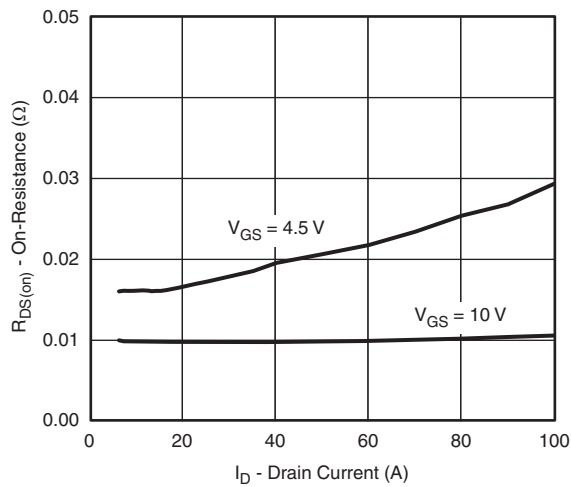
**TYPICAL CHARACTERISTICS** ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise noted)



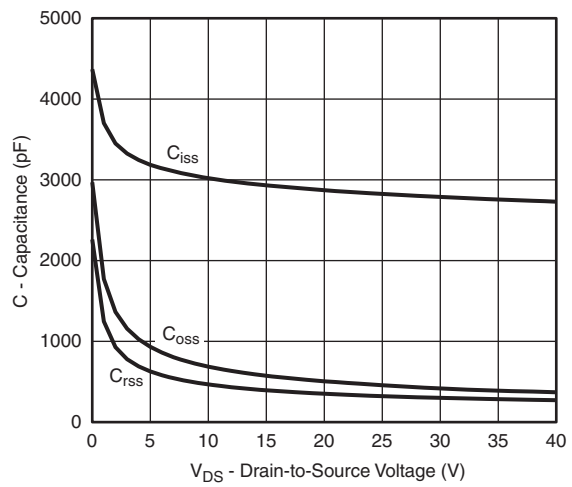
**Output Characteristics**



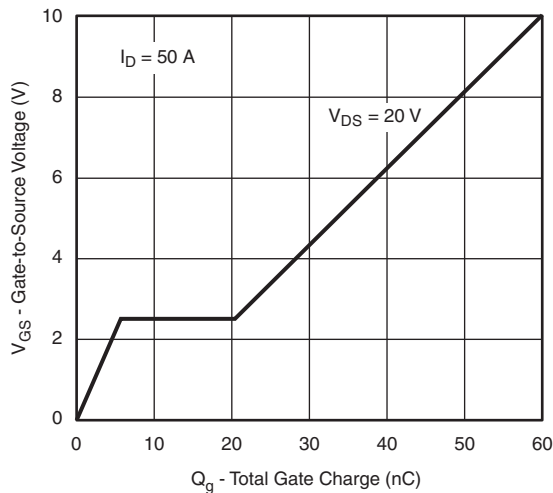
**Transfer Characteristics**



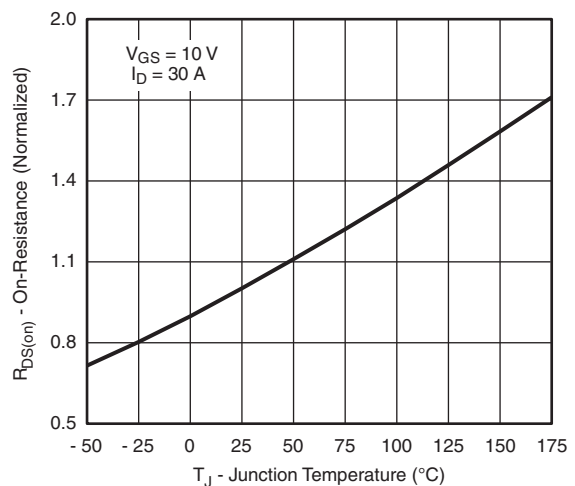
**On-Resistance vs. Drain Current**



**Capacitance**

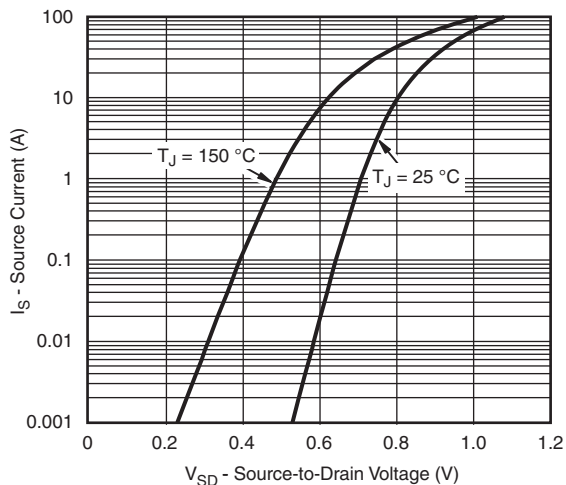


**Gate Charge**

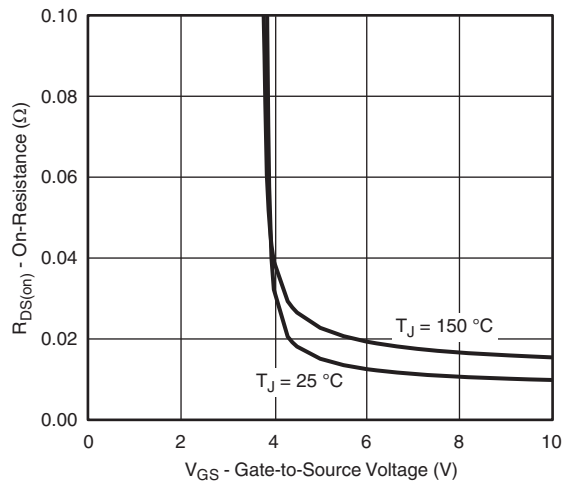


**On-Resistance vs. Junction Temperature**

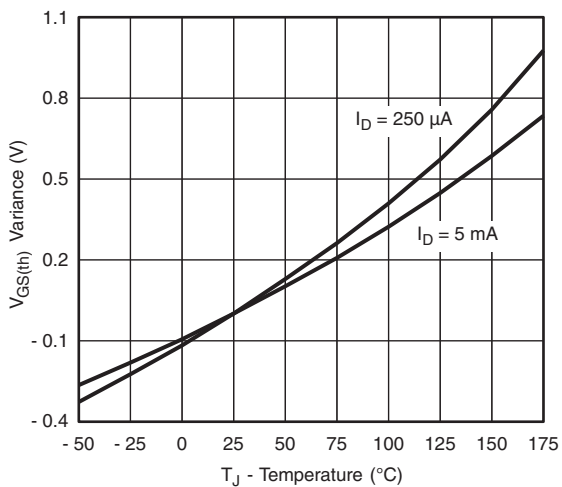
**TYPICAL CHARACTERISTICS** ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise noted)



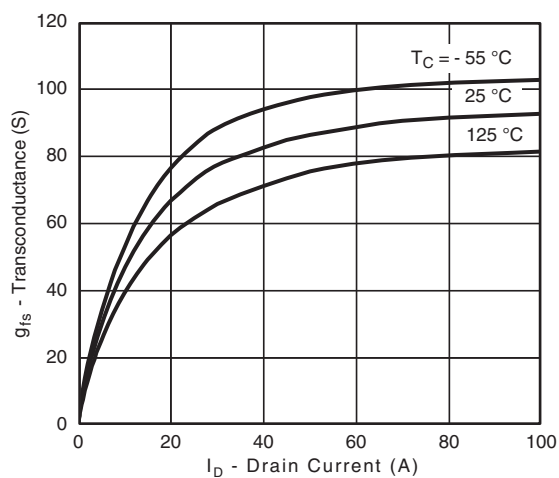
**Source Drain Diode Forward Voltage**



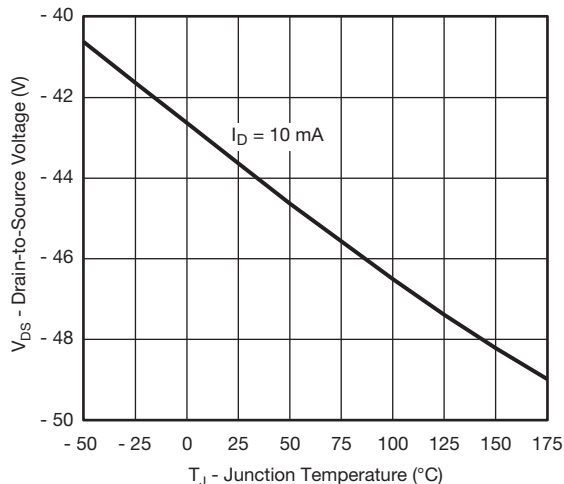
**On-Resistance vs. Gate-to Source Voltage**



**Threshold Voltage**

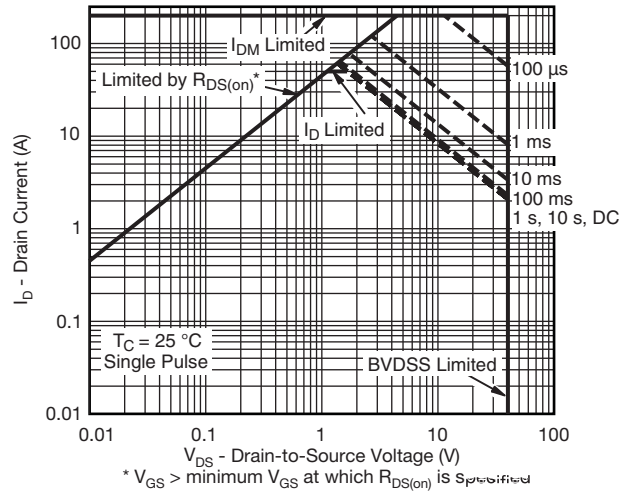


**Transconductance**

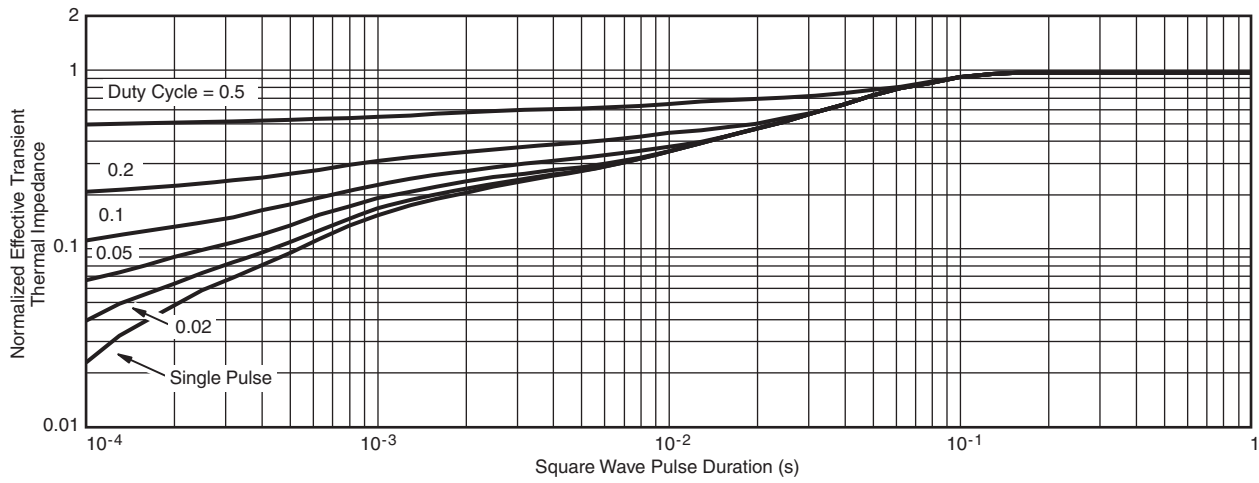


**Drain Source Breakdown vs. Junction Temperature**

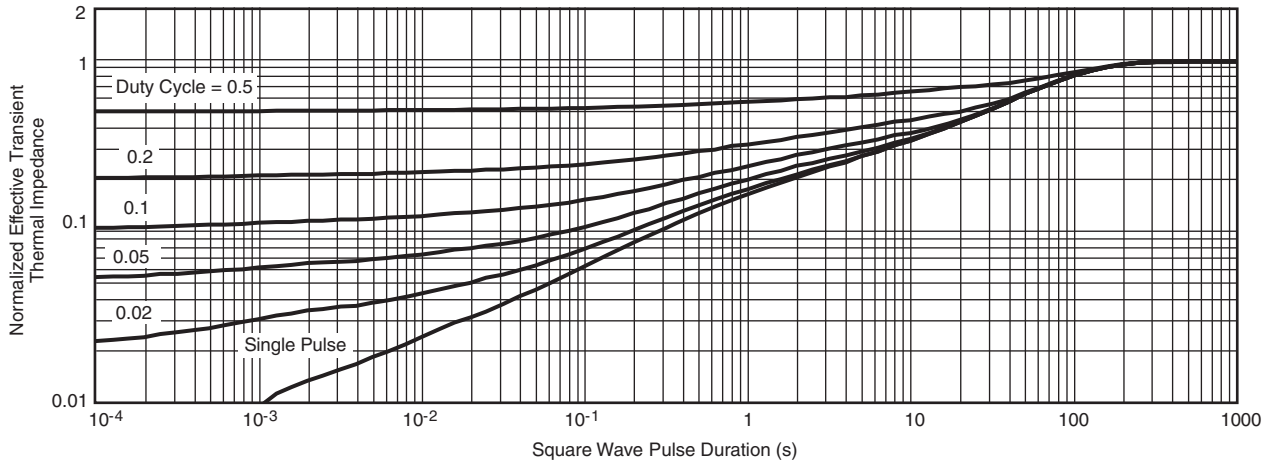
**TYPICAL CHARACTERISTICS** ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise noted)



**Safe Operating Area**



**Normalized Thermal Transient Impedance, Junction-to-Case**

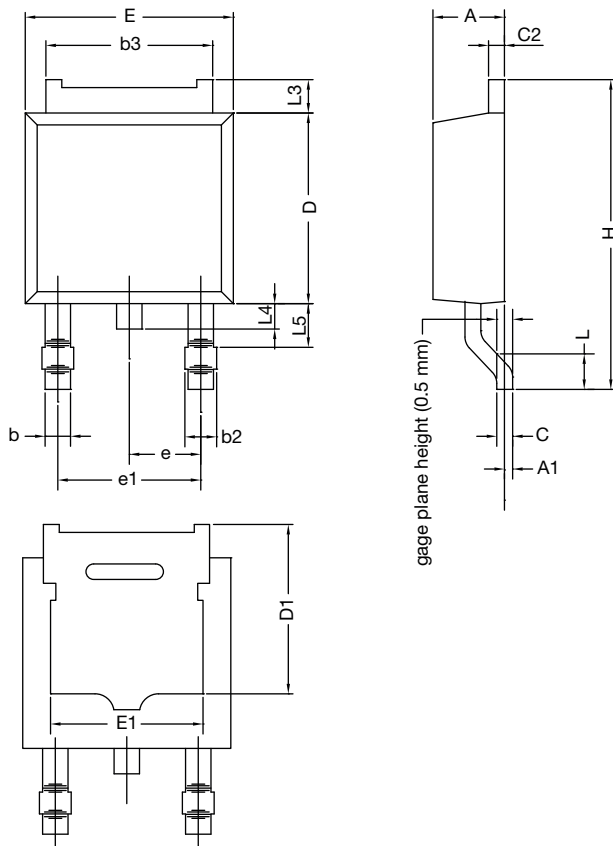


**Normalized Thermal Transient Impedance, Junction-to-Ambient**

**Note**

- The characteristics shown in the two graphs
    - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
    - Normalized Transient Thermal Impedance Junction-to-Case (25 °C)
- are given for general guidelines only to enable the user to get a “ball park” indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

## TO-252AA Case Outline

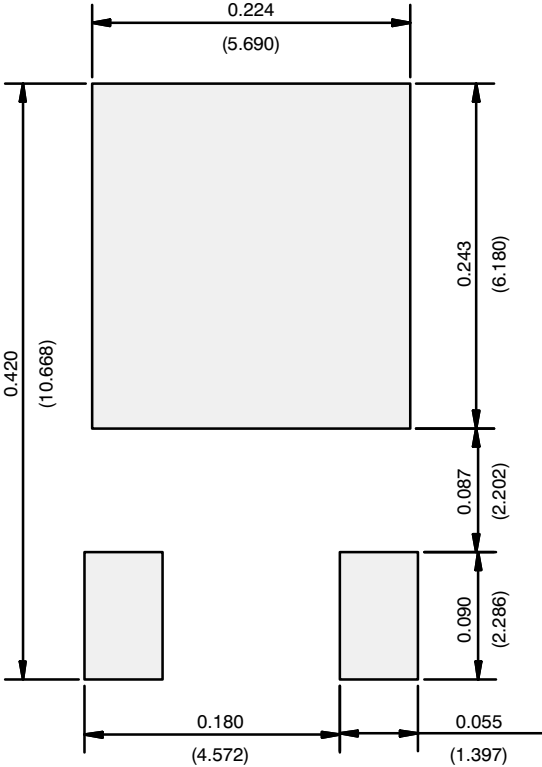


DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	2.18	2.38	0.086	0.094
A1	-	0.127	-	0.005
b	0.64	0.88	0.025	0.035
b2	0.76	1.14	0.030	0.045
b3	4.95	5.46	0.195	0.215
C	0.46	0.61	0.018	0.024
C2	0.46	0.89	0.018	0.035
D	5.97	6.22	0.235	0.245
D1	4.10	-	0.161	-
E	6.35	6.73	0.250	0.265
E1	4.32	-	0.170	-
H	9.40	10.41	0.370	0.410
e	2.28 BSC		0.090 BSC	
e1	4.56 BSC		0.180 BSC	
L	1.40	1.78	0.055	0.070
L3	0.89	1.27	0.035	0.050
L4	-	1.02	-	0.040
L5	1.01	1.52	0.040	0.060
ECN: T13-0592-Rev. A, 02-Sep-13 DWG: 6019				

**Note**

- Dimension L3 is for reference only.

RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads  
Dimensions in Inches/(mm)